Transaction Information

Tool ID	CMPO-A22
Tool Status	Connected
Location	Woodlands, Singapore
Wafer Size	200 mm
Fab Section	CMP
Tool Available Date	2024-10-09

General Product Information

Vendor Supplier	Ebara Corporation Tokyo Japan
Model	EPO-222
Vintage	2000
Serial No	PTG00638EX
Asset Description	Ebara 222 Oxide CMP-STI
Software Version	VME3.13.31/TouchPanel3.5.14
CIM	SECS/GEM
Process	Oxide ILD/IMD CMP

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Main System	PolishingCleaningUnit	2	OK
Handler System	RobotsRorze	2	OK
Options System			
Factory Interface	SMIF	2	OK
Others			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
NONE		

Missing/Faulty Parts / Accesorries List

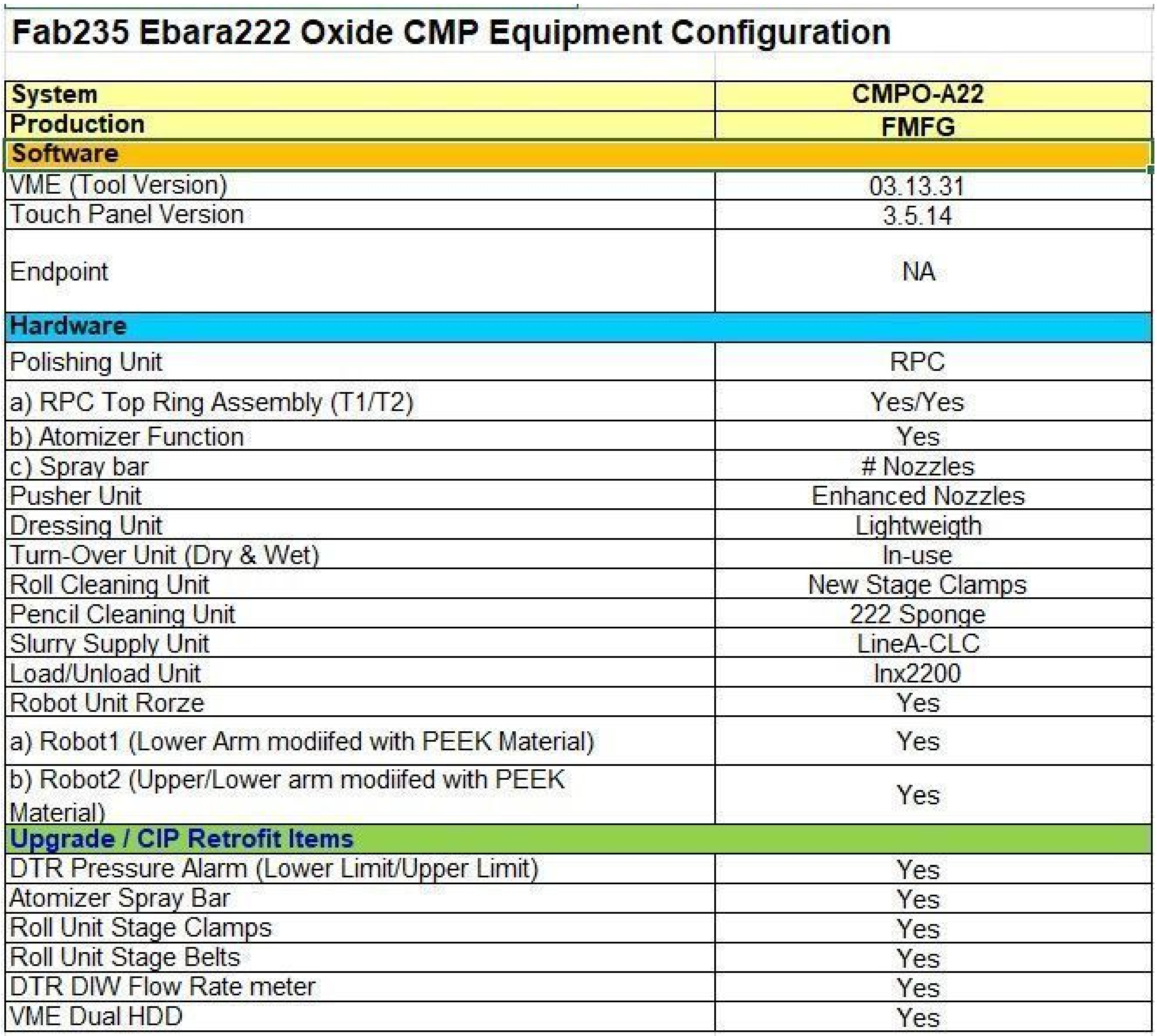
Description	Quantity
NONE	

Tool Pictures

General	PhysicalToolView

General	PhysicalToolView

Hardware Fab	ToolConfig



Fab235 Ebara222 Oxide CMP Equipment Configuration

System	**CMPO-A22**
Production	**FMFG**
Software	
VME (Tool Version)	03.13.31
Touch Panel Version	3.5.14
Endpoint	NA
Hardware	
Polishing Unit	RPC
a) RPC Top Ring Assembly (T1/T2)	Yes/Yes
b) Atomizer Function	Yes
c) Spray bar	# Nozzles
Pusher Unit	Enhanced Nozzles
Dressing Unit	Lightweigth
Turn-Over Unit (Dry & Wet)	In-use
Roll Cleaning Unit	New Stage Clamps
Pencil Cleaning Unit	222 Sponge
Slurry Supply Unit	LineA-CLC
Load/Unload Unit	Inx2200
Robot Unit Rorze	Yes
a) Robot1 (Lower Arm modiifed with PEEK Material)	Yes
b) Robot2 (Upper/Lower arm modiifed with PEEK Material)	Yes
Upgrade / CIP Retrofit Items	
DTR Pressure Alarm (Lower Limit/Upper Limit)	Yes
Atomizer Spray Bar	Yes
Roll Unit Stage Clamps	Yes
Roll Unit Stage Belts	Yes
DTR DIW Flow Rate meter	Yes
VME Dual HDD	Yes

Hardware Sub-fab	NoAuxiliary

No Auxiliary Equipment

Manufacture Serial	ToolSN

EBARA CMP

MODEL EPO 222

VOLTAGE 208 V

DATE 2000. 2

PHASE WIRE 3 PHASE 4 WIRES

SER. No PTG00638EX

FREQUENCY 50 Hz

CURRENT 125 A

EBARA

EBARA CORPORATION TOKYO JAPAN

U. S. PATENT
5,476,414 5,679,059
5,830,045 5,885,138

Missing Parts	NoMissingParts

ALL Parts are intact

Additional Tool Data Files

Fab235 Ebara222 Oxide CMP Equipment Configuration	
System	CMPO-A22
Production	FMFG
Software	
VME (Tool Version)	03.13.31
Touch Panel Version	3.5.14
Endpoint	NA
Hardware	
Polishing Unit	RPC
a) RPC Top Ring Assembly (T1/T2)	Yes/Yes
b) Atomizer Function	Yes
c) Spray bar	# Nozzles
Pusher Unit	Enhanced Nozzles
Dressing Unit	Lightweigth
Turn-Over Unit (Dry & Wet)	In-use
Roll Cleaning Unit	New Stage Clamps
Pencil Cleaning Unit	222 Sponge
Slurry Supply Unit	LineA-CLC
Load/Unload Unit	Inx2200
Robot Unit Rorze	Yes
a) Robot1 (Lower Arm modiifed with PEEK Material)	Yes
b) Robot2 (Upper/Lower arm modiifed with PEEK Material)	Yes
Upgrade / CIP Retrofit Items	
DTR Pressure Alarm (Lower Limit/Upper Limit)	Yes
Atomizer Spray Bar	Yes
Roll Unit Stage Clamps	Yes
Roll Unit Stage Belts	Yes
DTR DIW Flow Rate meter	Yes
VME Dual HDD	Yes